TEXAS INSTRUMENTS
SN74HCS595
ZHCSRP1B – OCTOBER 2020 – REVISED MAY 2021

SN74HCS595 具有施密特触发输入和三态输出寄存器的 8 位移位寄存器

1 特性

- 宽工作电压范围：2V 至 6V
- 施密特触发输入可实现慢速或高噪声输入信号
- 低功耗
  - I_{CC} 典型值为 100nA
  - 输入泄漏电流典型值为 ±100nA
- 电压为 6V 时，输出驱动为 ±7.8mA
- 工作环境温度范围：–40°C 至 +125°C，T_A

2 应用

- 输出扩展
- LED 矩阵控制
- 7 段显示控制
- 8 位数据存储

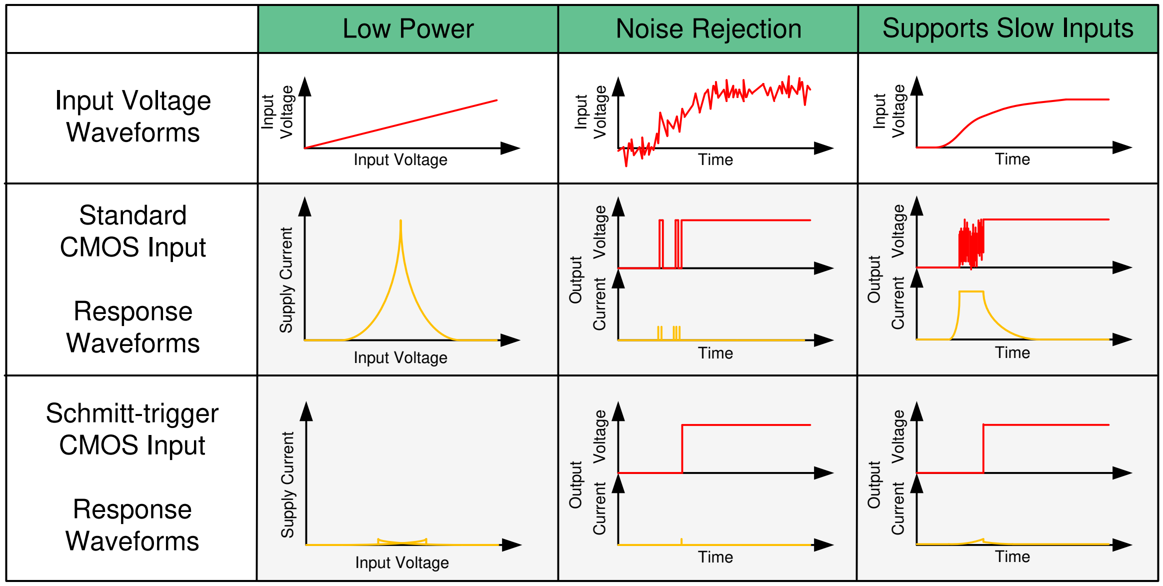
3 说明

SN74HCS595 器件包含对 8 位 D 类存储寄存器进行馈送的 8 位串行输入、并行输出移位寄存器。所有输入均包括施密特触发架构，因此消除了由边沿变化缓慢或高噪声输入信号导致的任何错误数据输出。存储寄存器具有并行三态输出。移位寄存器和存储寄存器分别有单独的时钟。移位寄存器具有一个直接覆盖清零 ($\overline{\text{SRCLR}}$) 的串行 (SER) 输入和一个串行输出 ($Q_{H'}$)，以用于级联。当输出使能端 ($\overline{\text{OE}}$) 输入为高电平时，存储寄存器输出处于高阻抗状态。内部寄存器数据和串行输出 ($Q_{H'}$) 不受 $\overline{\text{OE}}$ 端输入的影响。

器件信息

器件型号	封装[1]	封装尺寸（标称值）
SN74HCS595PW	TSSOP (16)	5.00mm x 4.40mm
SN74HCS595D	SOIC (16)	9.90mm x 3.90mm
SN74HCS595BQB	WQFN (16)	3.60 mm x 2.60 mm
SN74HCS595DYY	SOT-23-THN (16)	4.20mm x 2.00mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



施密特触发输入的优势

English Data Sheet: SCLS803

Table of Contents

---

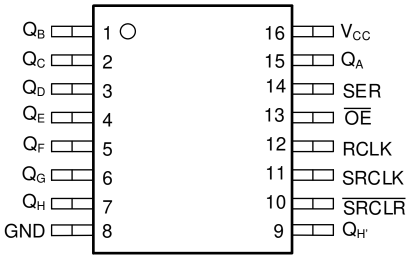
4 Revision History

注：以前版本的页码可能与当前版本的页码不同

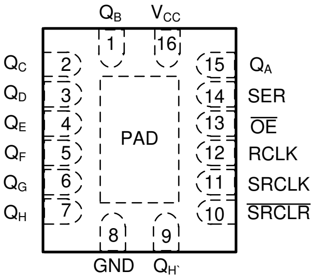
Changes from Revision * (August 2020) to Revision A (October 2020)	Page
• 将 BQB 和 D 封装的状态更改为“正在供货”	1
• 将数据表状态更改为“量产数据”	1

Changes from Revision A (October 2020) to Revision B (May 2021)	Page
• 在*器件信息* 表中添加了 DYY 封装	1
• Added DYY Package pinout diagram and information to *Pin Configuration and Functions*	3
• Added DYY Package to *Thermal Information* table	4

5 Pin Configuration and Functions



D, PW, or DYY Package
16-Pin SOIC, TSSOP, or SOT-23
Top View



BQB Package
16-Pin WQFN
Transparent Top View

引脚功能

引脚		类型	说明
名称	编号		
Q_B	1	输出	Q_B 输出
Q_C	2	输出	Q_C 输出
Q_D	3	输出	Q_D 输出
Q_E	4	输出	Q_E 输出
Q_F	5	输出	Q_F 输出
Q_G	6	输出	Q_G 输出
Q_H	7	输出	Q_H 输出
GND	8	—	接地
$Q_{H'}$	9	输出	串行输出，可用于级联
$\overline{\text{SRCLR}}$	10	输入	移位寄存器清零，低电平有效
SRCLK	11	输入	移位寄存器时钟，上升沿触发
RCLK	12	输入	输出寄存器时钟，上升沿触发
$\overline{\text{OE}}$	13	输入	输出使能，低电平有效
SER	14	输入	串行输入
Q_A	15	输出	Q_A 输出
V_{CC}	16	—	正电源
散热焊盘(1)		—	散热焊盘可连接到 GND 或悬空。请勿连接到任何其他信号或电源。

1. 仅限 BQB 封装。

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		–0.5	7	V
I_{IK}	Input clamp current(2)	$V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V		±20	mA
I_{OK}	Output clamp current(2)	$V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V		±20	mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}		±35	mA
	Continuous current through V_{CC} or GND			±70	mA
T_J	Junction temperature(3)			150	°C
T_{stg}	Storage temperature		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
(3) Guaranteed by design.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±4000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	2	5	6	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
T_A	Ambient temperature	–40		125	°C

6.4 Thermal Information

THERMAL METRIC(1)		SN74HCS595				UNIT
		PW (TSSOP)	D (SOIC)	BQB (WQFN)	DYY (SOT-23)	
		16 PINS	16 PINS	16 PINS	16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	141.2	122.2	108.4	186.2	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	78.8	80.9	77.3	109.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	85.8	80.6	74.4	111.0	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	27.7	40.4	12.6	18.0	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	85.5	80.3	74.5	110.9	°C/W

THERMAL METRIC[1]		SN74HCS595				UNIT
		PW (TSSOP)	D (SOIC)	BQB (WQFN)	DYY (SOT-23)	
		16 PINS	16 PINS	16 PINS	16 PINS	
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	54.3	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.5 Electrical Characteristics

over operating free-air temperature range; typical values measured at T_A = 25°C (unless otherwise noted).

PARAMETER		TEST CONDITIONS		V_{CC}	MIN	TYP	MAX	UNIT
V_{T+}	Positive switching threshold			2 V	0.7		1.5	V
				4.5 V	1.7		3.15	
				6 V	2.1		4.2	
V_{T-}	Negative switching threshold			2 V	0.3		1.0	V
				4.5 V	0.9		2.2	
				6 V	1.2		3.0	
ΔV_T	Hysteresis (V_{T+} - V_{T-})[1]			2 V	0.2		1.0	V
				4.5 V	0.4		1.4	
				6 V	0.6		1.6	
V_{OH}	High-level output voltage	$V_I = V_{IH}$ or V_{IL}	I_{OH} = -20 µA	2 V to 6 V	V_{CC} – 0.1	V_{CC} – 0.002		V
			I_{OH} = -6 mA	4.5 V	4.0	4.3		
			I_{OH} = -7.8 mA	6 V	5.4	5.75		
V_{OL}	Low-level output voltage	$V_I = V_{IH}$ or V_{IL}	I_{OL} = 20 µA	2 V to 6 V		0.002	0.1	V
			I_{OL} = 6 mA	4.5 V		0.18	0.30	
			I_{OL} = 7.8 mA	6 V		0.22	0.33	
I_I	Input leakage current	$V_I = V_{CC}$ or 0		6 V		±0.1	±1	µA
I_{OZ}	Off-state (high-impedance state) output current	$V_O = V_{CC}$ or 0		6 V		±0.5	±5	µA
I_{CC}	Supply current	$V_I = V_{CC}$ or 0, I_O = 0		6 V		0.1	2	µA
C_i	Input capacitance			2 V to 6 V			5	pF

(1) Guaranteed by design.

6.6 Timing Characteristics

C_L = 50 pF; over operating free-air temperature range (unless otherwise noted). See Parameter Measurement Information.

PARAMETER			V_{CC}	Operating free-air temperature (T_A)				UNIT
				25°C		–40°C to 125°C		
				MIN	MAX	MIN	MAX	
t_w	Pulse duration	SRCLK or RCLK high or low	2 V	7		9		ns
			4.5 V	7		7		
			6 V	7		7		
		$\overline{\text{SRCLR}}$ low	2 V	8		10		
			4.5 V	7		7		
			6 V	7		7		

C_L = 50 pF; over operating free-air temperature range (unless otherwise noted). See Parameter Measurement Information.

PARAMETER			V_{CC}	Operating free-air temperature (T_A)				UNIT
				25°C		–40°C to 125°C		
				MIN	MAX	MIN	MAX	
t_{su}	Setup time	SER before SRCLK ↑	2 V	8		13		ns
			4.5 V	4		5		
			6 V	3		4		
		SRCLK ↑ before RCLK ↑	2 V	11		18		
			4.5 V	5		7		
			6 V	4		6		
		$\overline{\text{SRCLR}}$ low before RCLK ↑	2 V	8		13		
			4.5 V	4		6		
			6 V	4		5		
		$\overline{\text{SRCLR}}$ high (inactive) before SRCLK ↑	2 V	8		13		
			4.5 V	4		6		
			6 V	4		5		
t_h	Hold time	SER after SRCLK ↑	2 V	0		0		ns
			4.5 V	0		0		
			6 V	0		0		

6.7 Switching Characteristics

C_L = 50 pF; over operating free-air temperature range (unless otherwise noted). See Parameter Measurement Information.

PARAMETER		FROM	TO	V_{CC}	Operating free-air temperature (T_A)						UNIT
					25°C			–40°C to 125°C			
					MIN	TYP	MAX	MIN	TYP	MAX	
f_{max}	Max switching frequency			2 V	35			19			MHz
				4.5 V	110			60			
				6 V	130			75			
t_{pd}	Propagation delay	SRCLK	$Q_{H'}$	2 V		14	19			28	ns
				4.5 V		6	8			10	
				6 V		5	7			9	
		RCLK	Q_A - Q_H	2 V		16	21			37	
				4.5 V		6	9			12	
				6 V		6	8			10	
t_{PHL}	Propagation delay	$\overline{\text{SRCLR}}$	$Q_{H'}$	2 V		13	19			27	ns
				4.5 V		6	8			11	
				6 V		6	8			10	
t_{en}	Enable time	$\overline{\text{OE}}$	Q_A - Q_H	2 V		12	18			27	ns
				4.5 V		6	9			13	
				6 V		5	8			11	
t_{dis}	Disable time	$\overline{\text{OE}}$	Q_A - Q_H	2 V		13	16			20	ns
				4.5 V		9	11			13	
				6 V		8	10			12	
t_t	Transition-time		Any output	2 V			9			16	ns
				4.5 V			5			9	
				6 V			4			8	

6.8 Operating Characteristics

over operating free-air temperature range; typical values measured at T_A = 25°C (unless otherwise noted).

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
C_{pd}	Power dissipation capacitance per gate	No load	2 V to 6 V		40		pF

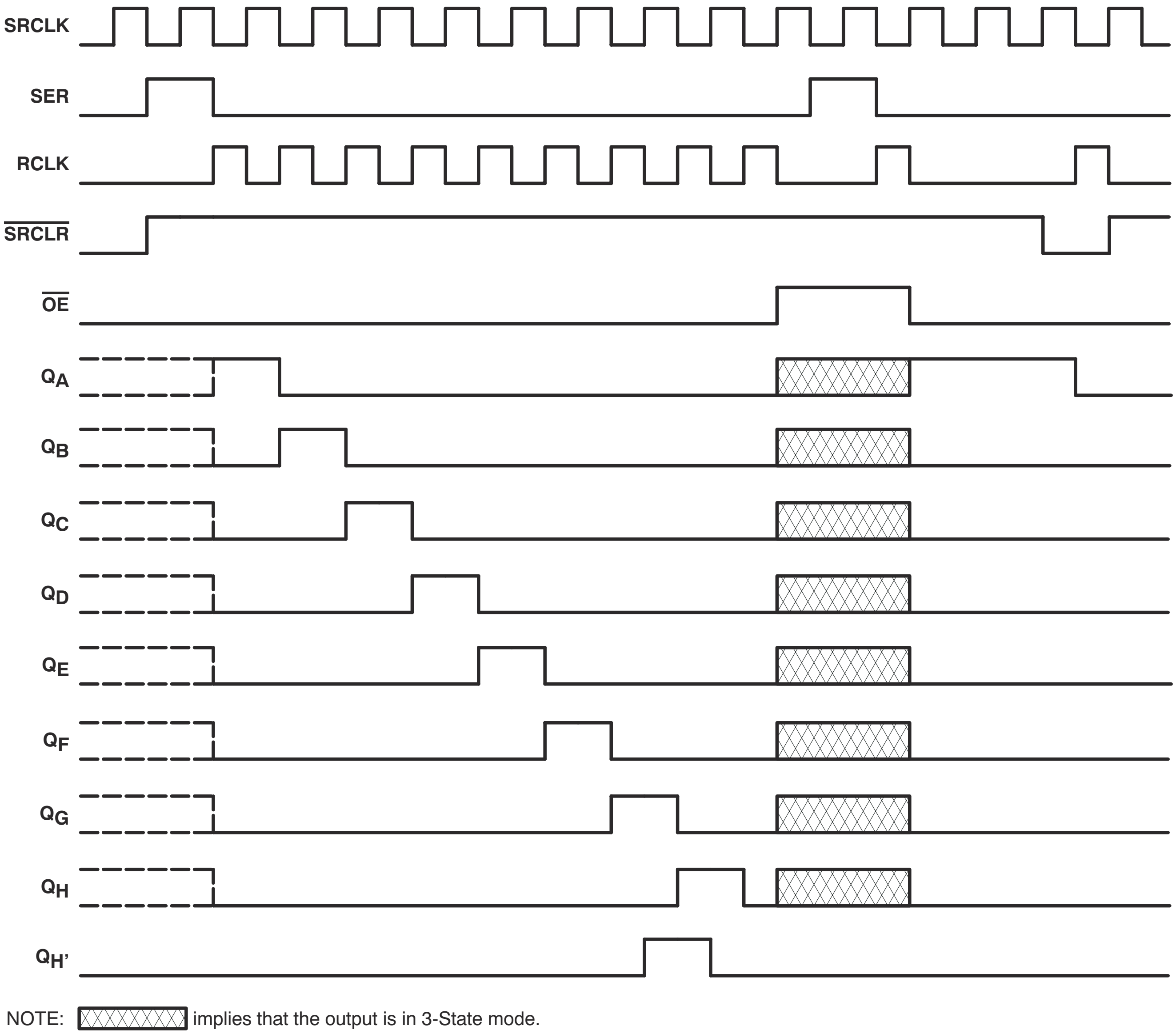


图 6-1. Timing Diagram

6.9 Typical Characteristics

T_A = 25°C

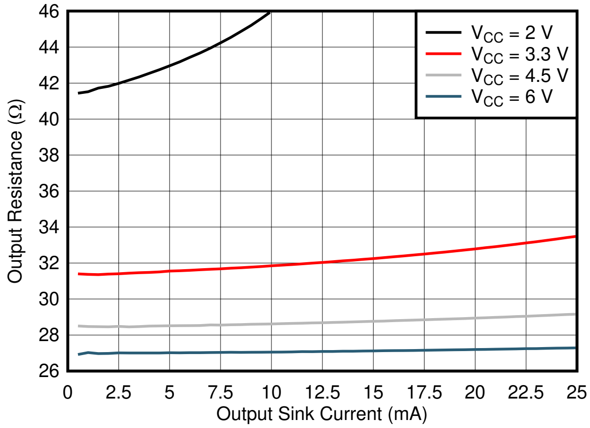


图 **6-2. Output driver resistance in LOW state.**

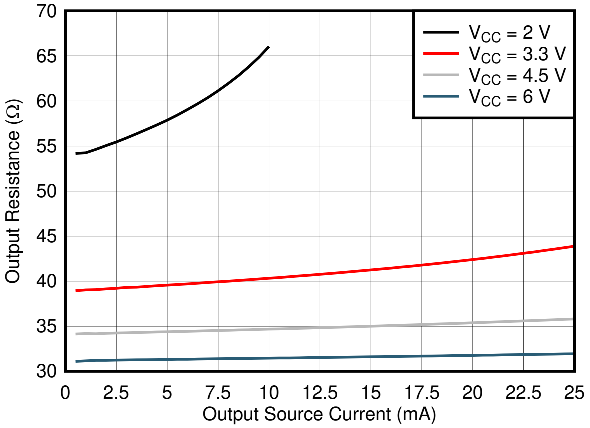


图 **6-3. Output driver resistance in HIGH state.**

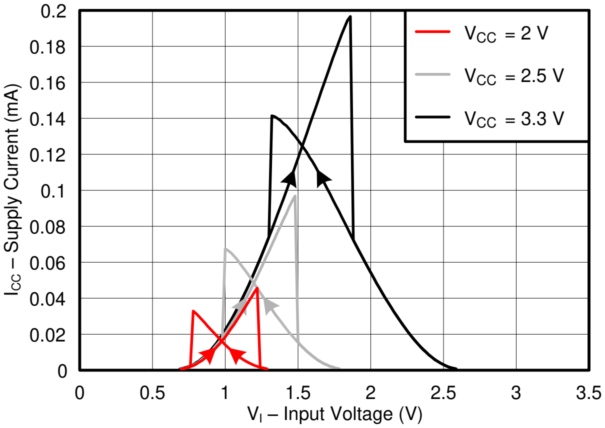


图 **6-4. Supply current across input voltage, 2-, 2.5-, and 3.3-V supply**

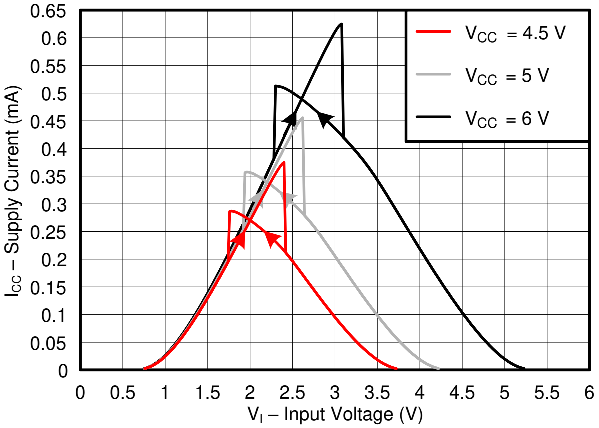


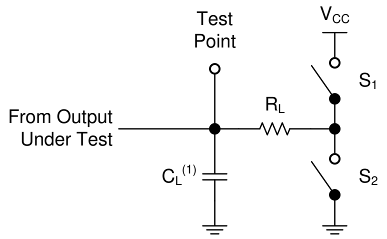
图 **6-5. Supply current across input voltage, 4.5-, 5-, and 6-V supply**

7 Parameter Measurement Information

Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ⩽ 1 MHz, Z_O = 50 Ω, t_t < 2.5 ns.

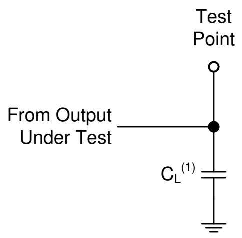
For clock inputs, f_{max} is measured when the input duty cycle is 50%.

The outputs are measured one at a time with one input transition per measurement.



(1) C_L includes probe and test-fixture capacitance.

图 7-1. Load Circuit for 3-State Outputs



(1) C_L includes probe and test-fixture capacitance.

图 7-2. Load Circuit for Push-Pull Outputs

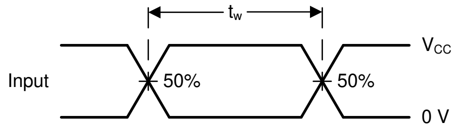


图 7-3. Voltage Waveforms, Pulse Duration

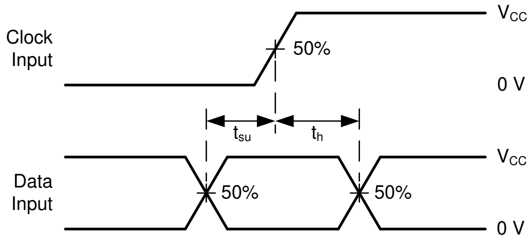
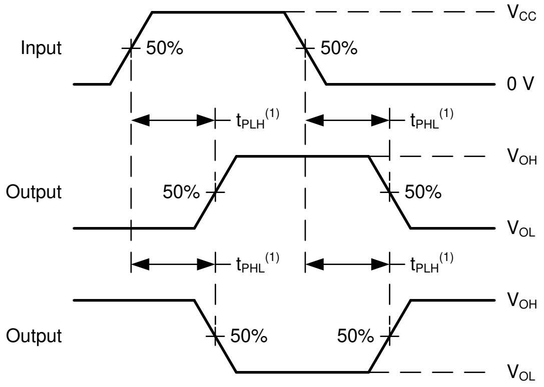


图 7-4. Voltage Waveforms, Setup and Hold Times



(1) The greater between t_{PLH} and t_{PHL} is the same as t_{pd}.

图 7-5. Voltage Waveforms Propagation Delays

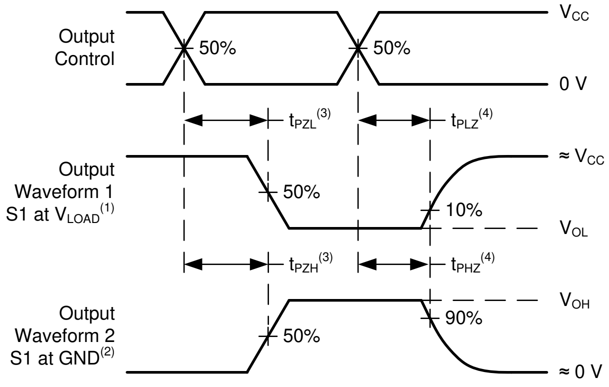
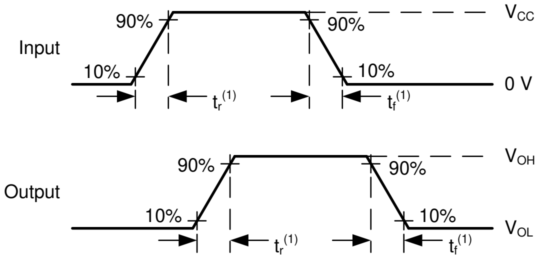


图 7-6. Voltage Waveforms Propagation Delays



(1) The greater between t_r and t_f is the same as t_t.

图 7-7. Voltage Waveforms, Input and Output Transition Times

8 Detailed Description

8.1 Functional Block Diagram

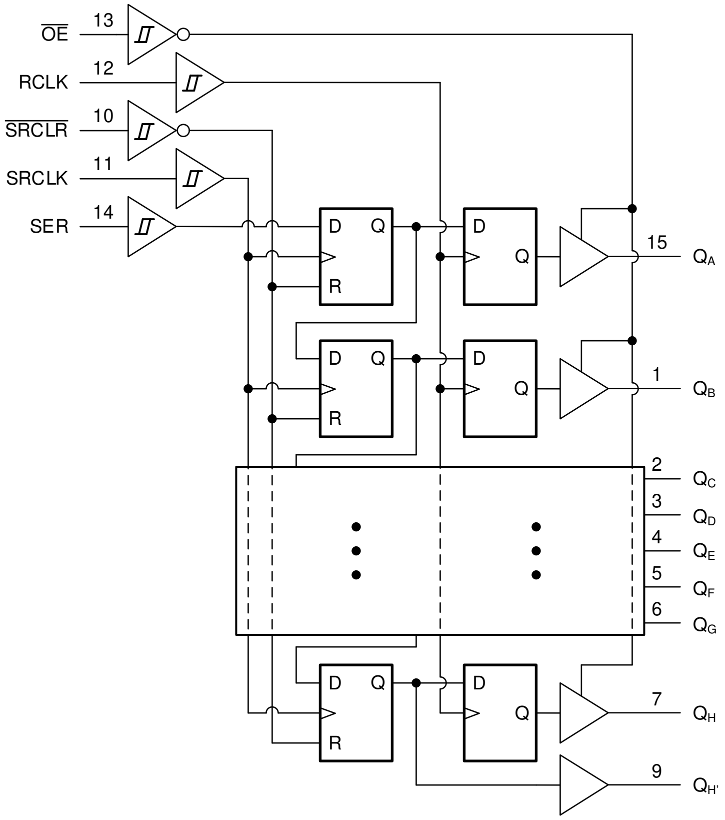


图 8-1. Logic Diagram (Positive Logic) for the SN74HCS595

8.2 Feature Description

8.2.1 Balanced CMOS 3-State Outputs

This device includes balanced CMOS 3-State outputs. The three states that these outputs can be in are driving high, driving low, and high impedance. The term "balanced" indicates that the device can sink and source similar currents. The drive capability of this device may create fast edges into light loads so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important for the output power of the device to be limited to avoid damage due to overcurrent. The electrical and thermal limits defined in the *Absolute Maximum Ratings* must be followed at all times.

When placed into the high-impedance mode, the output will neither source nor sink current, with the exception of minor leakage current as defined in the *Electrical Characteristics* table. In the high-impedance state, the output voltage is not controlled by the device and is dependent on external factors. If no other drivers are connected to the node, then this is known as a floating node and the voltage is unknown. A pull-up or pull-down resistor can be connected to the output to provide a known voltage at the output while it is in the high-impedance state. The value of the resistor will depend on multiple factors, including parasitic capacitance and power consumption limitations. Typically, a 10 kΩ resistor can be used to meet these requirements.

Unused 3-state CMOS outputs should be left disconnected.

8.2.2 Balanced CMOS Push-Pull Outputs

This device includes balanced CMOS push-pull outputs. The term "balanced" indicates that the device can sink and source similar currents. The drive capability of this device may create fast edges into light loads so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important for the output power of the device to be limited to avoid damage due to overcurrent. The electrical and thermal limits defined in the *Absolute Maximum Ratings* must be followed at all times.

Unused push-pull CMOS outputs should be left disconnected.

8.2.3 Latching Logic

This device includes latching logic circuitry. Latching circuits commonly include D-type latches and D-type flip-flops, but include all logic circuits that act as volatile memory.

When the device is powered on, the state of each latch is unknown. There is no default state for each latch at start-up.

The output state of each latching logic circuit only remains stable as long as power is applied to the device within the supply voltage range specified in the *Recommended Operating Conditions* table.

8.2.4 Clamp Diode Structure

The inputs and outputs to this device have both positive and negative clamping diodes as depicted in Electrical Placement of Clamping Diodes for Each Input and Output.

> **CAUTION**
>
> Voltages beyond the values specified in the *Absolute Maximum Ratings* table can cause damage to the device. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

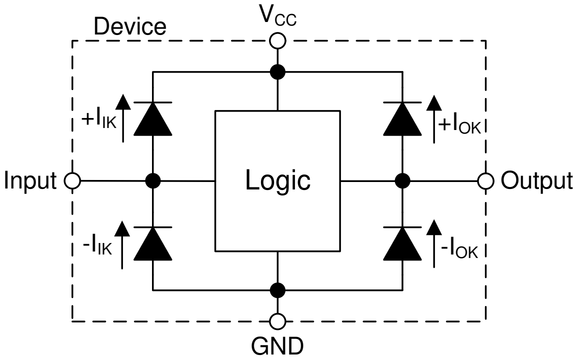


图 8-2. Electrical Placement of Clamping Diodes for Each Input and Output

8.3 Device Functional Modes

Function Table lists the functional modes of the SN74HCS595.

表 8-1. Function Table

INPUTS					FUNCTION
SER	**SRCLK**	**$\overline{SRCLR}$**	**RCLK**	**$\overline{OE}$**	
X	X	X	X	H	Outputs Q_A – Q_H are disabled
X	X	X	X	L	Outputs Q_A – Q_H are enabled.
X	X	L	X	X	Shift register is cleared.
L	↑	H	X	X	First stage of the shift register goes low. Other stages store the data of previous stage, respectively.
H	↑	H	X	X	First stage of the shift register goes high. Other stages store the data of previous stage, respectively.
X	X	H	↑	X	Shift-register data is stored in the storage register.

表 8-1. Function Table (continued)

INPUTS					**FUNCTION**
SER	**SRCLK**	**$\overline{\text{SRCLR}}$**	**RCLK**	**$\overline{\text{OE}}$**	
X	↑	H	↑	X	Data in shift register is stored in the storage register, the data is then shifted through.

9 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客 户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

9.1 Application Information

In this application, the SN74HCS595 is used to control seven-segment displays. Utilizing the serial output and combining a few of the input signals, this implementation reduces the number of I/O pins required to control the displays from sixteen to four. Unlike other I/O expanders, the SN74HCS595 does not need a communication interface for control. It can be easily operated with simple GPIO pins.

The OE pin is used to easily disable the outputs when the displays need to be turned off or connected to a PWM signal to control brightness. However, this pin can be tied low and the outputs of the SN74HCS595 can be controlled accordingly to turn off all the outputs reducing the I/O needed to three. There is no practical limitation to how many SN74HCS595 devices can be cascaded. To add more, the serial output will need to be connected to the following serial input and the clocks will need to be connected accordingly. With separate control for the shift registers and output registers, the desired digit can be displayed while the data for the next digit is loaded into the shift register.

At power-up, the initial state of the shift registers and output registers are unknown. To give them a defined state, the shift register needs to be cleared and then clocked into the output register. An RC can be connected to the $\overline{\text{SRCLR}}$ pin as shown in the Typical application block diagram to initialize the shift register to all zeros. With the $\overline{\text{OE}}$ pin pulled up with a resistor, this process can be performed while the outputs are in a high impedance state eliminating any erroneous data causing issues with the displays.

9.2 Typical Application

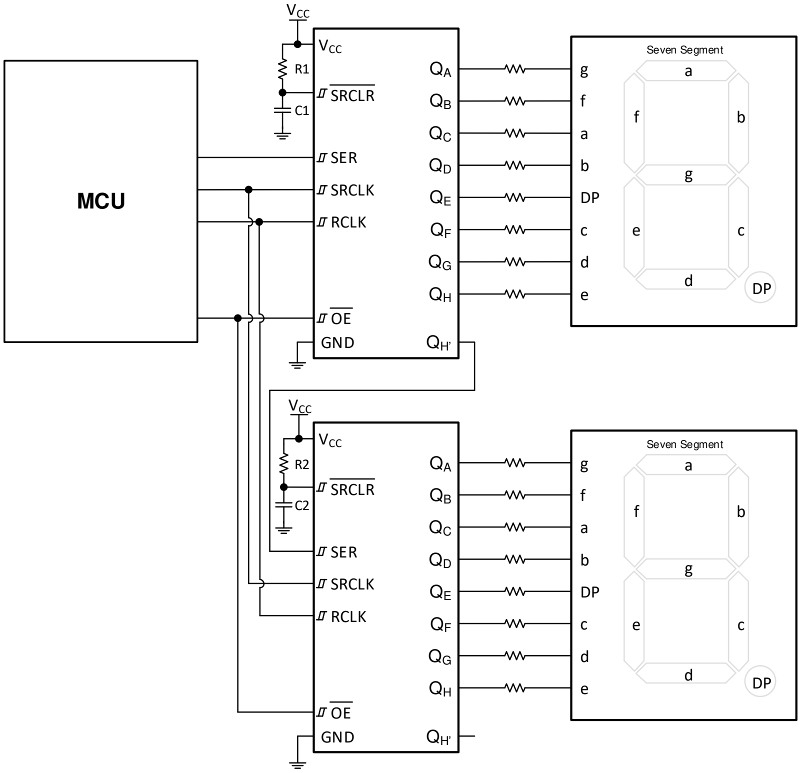


图 9-1. Typical application block diagram

9.2.1 Design Requirements

9.2.1.1 Power Considerations

Ensure the desired supply voltage is within the range specified in the *Recommended Operating Conditions*. The supply voltage sets the device's electrical characteristics as described in the *Electrical Characteristics*.

The positive voltage supply must be capable of sourcing current equal to the total current to be sourced by all outputs of the SN74HCS595 plus the maximum static supply current, I_{CC}, listed in *Electrical Characteristics* and any transient current required for switching. The logic device can only source as much current as is provided by the positive supply source. Be sure not to exceed the maximum total current through V_{CC} listed in the *Absolute Maximum Ratings*.

The ground must be capable of sinking current equal to the total current to be sunk by all outputs of the SN74HCS595 plus the maximum supply current, I_{CC}, listed in *Electrical Characteristics*, and any transient current required for switching. The logic device can only sink as much current as can be sunk into its ground connection. Be sure not to exceed the maximum total current through GND listed in the *Absolute Maximum Ratings*.

The SN74HCS595 can drive a load with a total capacitance less than or equal to 50 pF while still meeting all of the datasheet specifications. Larger capacitive loads can be applied, however it is not recommended to exceed 50 pF.

The SN74HCS595 can drive a load with total resistance described by $R_L \geqslant V_O / I_O$, with the output voltage and current defined in the *Electrical Characteristics* table with V_{OH} and V_{OL}. When outputting in the high state, the output voltage in the equation is defined as the difference between the measured output voltage and the supply voltage at the V_{CC} pin.

Total power consumption can be calculated using the information provided in CMOS Power Consumption and Cpd Calculation.

Thermal increase can be calculated using the information provided in Thermal Characteristics of Standard Linear and Logic (SLL) Packages and Devices.

> **CAUTION**
>
> The maximum junction temperature, $T_{J(max)}$ listed in the *Absolute Maximum Ratings*, is an additional limitation to prevent damage to the device. Do not violate any values listed in the *Absolute Maximum Ratings*. These limits are provided to prevent damage to the device.

9.2.1.2 Input Considerations

Input signals must cross $V_{t-(min)}$ to be considered a logic LOW, and $V_{t+(max)}$ to be considered a logic HIGH. Do not exceed the maximum input voltage range found in the *Absolute Maximum Ratings*.

Unused inputs must be terminated to either V_{CC} or ground. These can be directly terminated if the input is completely unused, or they can be connected with a pull-up or pull-down resistor if the input is to be used sometimes, but not always. A pull-up resistor is used for a default state of HIGH, and a pull-down resistor is used for a default state of LOW. The resistor size is limited by drive current of the controller, leakage current into the SN74HCS595, as specified in the *Electrical Characteristics*, and the desired input transition rate. A 10-kΩ resistor value is often used due to these factors.

The SN74HCS595 has no input signal transition rate requirements because it has Schmitt-trigger inputs.

Another benefit to having Schmitt-trigger inputs is the ability to reject noise. Noise with a large enough amplitude can still cause issues. To know how much noise is too much, please refer to the $\Delta V_{T(min)}$ in the *Electrical Characteristics*. This hysteresis value will provide the peak-to-peak limit.

Unlike what happens with standard CMOS inputs, Schmitt-trigger inputs can be held at any valid value without causing huge increases in power consumption. The typical additional current caused by holding an input at a value other than V_{CC} or ground is plotted in the *Typical Characteristics*.

Refer to the *Feature Description* section for additional information regarding the inputs for this device.

9.2.1.3 Output Considerations

The positive supply voltage is used to produce the output HIGH voltage. Drawing current from the output will decrease the output voltage as specified by the V_{OH} specification in the *Electrical Characteristics*. The ground voltage is used to produce the output LOW voltage. Sinking current into the output will increase the output voltage as specified by the V_{OL} specification in the *Electrical Characteristics*.

Push-pull outputs that could be in opposite states, even for a very short time period, should never be connected directly together. This can cause excessive current and damage to the device.

Two channels within the same device with the same input signals can be connected in parallel for additional output drive strength.

Unused outputs can be left floating. Do not connect outputs directly to V_{CC} or ground.

Refer to *Feature Description* section for additional information regarding the outputs for this device.

9.2.2 Detailed Design Procedure

1. Add a decoupling capacitor from V_{CC} to GND. The capacitor needs to be placed physically close to the device and electrically close to both the V_{CC} and GND pins. An example layout is shown in the *Layout* section.
2. Ensure the capacitive load at the output is ⩽ 50 pF. This is not a hard limit, however it will ensure optimal performance. This can be accomplished by providing short, appropriately sized traces from the SN74HCS595 to the receiving device(s).
3. Ensure the resistive load at the output is larger than $(V_{CC} / I_{O(max)})\ \Omega$. This will ensure that the maximum output current from the *Absolute Maximum Ratings* is not violated. Most CMOS inputs have a resistive load measured in megaohms; much larger than the minimum calculated above.
4. Thermal issues are rarely a concern for logic gates, however the power consumption and thermal increase can be calculated using the steps provided in the application report, CMOS Power Consumption and Cpd Calculation.

9.2.3 Application Curve

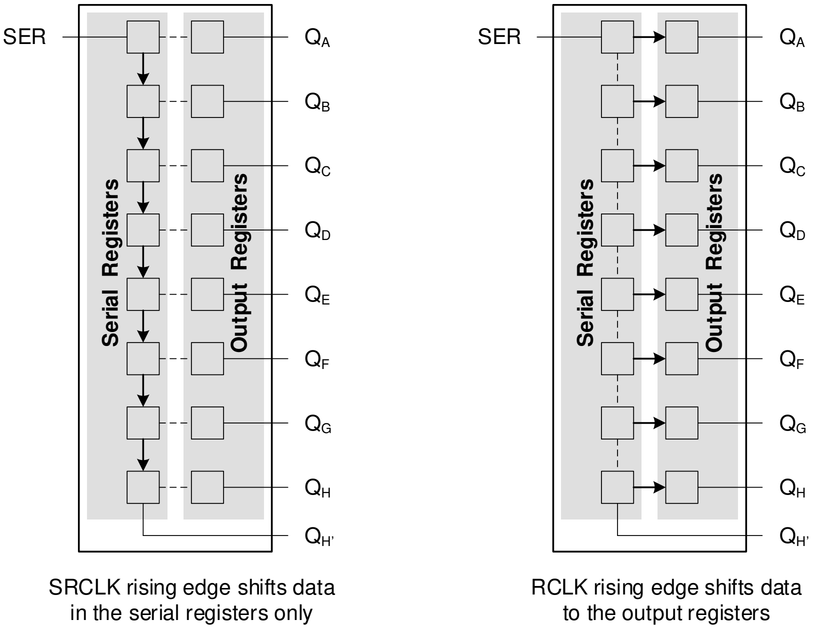


图 9-2. Simplified functional diagram showing clock operation

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1-μF capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1-μF and 1-μF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results, as shown in given example layout image.

11 Layout

11.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC}, whichever makes more sense for the logic function or is more convenient.

11.2 Layout Example

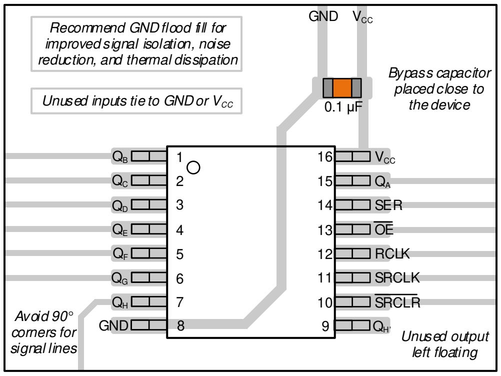


图 11-1. Example layout for the SN74HCS595.

12 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, *HCMOS Design Considerations* application report (SCLA007)
- Texas Instruments, *CMOS Power Consumption and C_{pd} Calculation* application report (SDYA009)
- Texas Instruments, *Designing With Logic* application report

12.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击*订阅更新* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

12.3 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

12.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

12.5 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

12.6 术语表

TI 术语表	本术语表列出并解释了术语、首字母缩略词和定义。

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

重要声明和免责声明

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74HCS595BQBR	Active	Production	WQFN (BQB) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HCS595
SN74HCS595BQBR.A	Active	Production	WQFN (BQB) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HCS595
SN74HCS595DR	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	HCS595
SN74HCS595DR.A	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HCS595
SN74HCS595DR.B	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HCS595
SN74HCS595DYYR	Active	Production	SOT-23-THIN (DYY) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HCS595
SN74HCS595DYYR.A	Active	Production	SOT-23-THIN (DYY) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HCS595
SN74HCS595PWR	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	HCS595
SN74HCS595PWR.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HCS595
SN74HCS595PWR.B	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HCS595

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

PACKAGE OPTION ADDENDUM

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

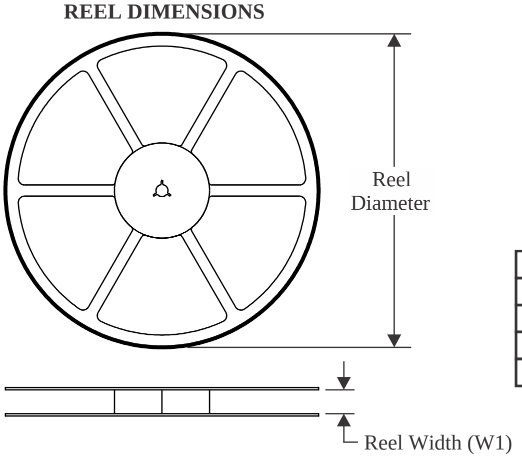
OTHER QUALIFIED VERSIONS OF SN74HCS595 :

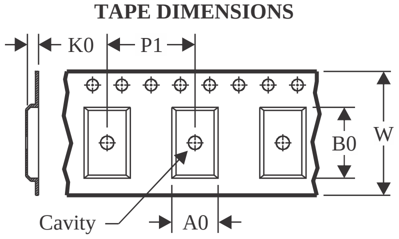
- Automotive : SN74HCS595-Q1

NOTE: Qualified Version Definitions:

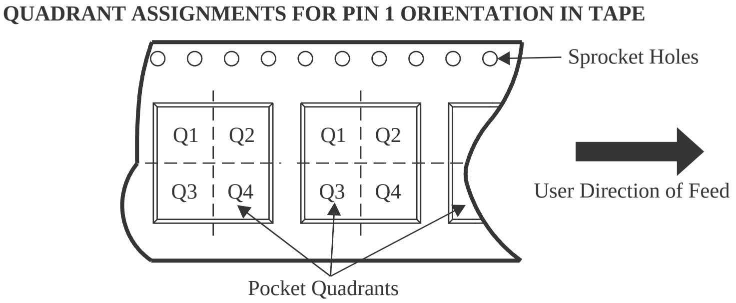
  - Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION





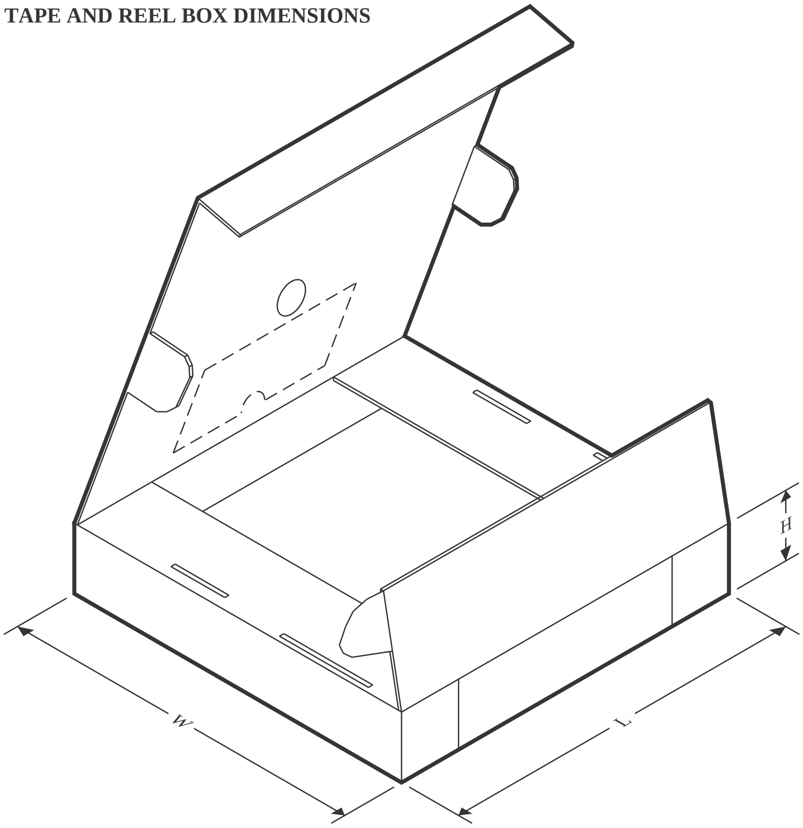
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCS595BQBR	WQFN	BQB	16	3000	180.0	12.4	2.8	3.8	1.2	4.0	12.0	Q1
SN74HCS595DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HCS595DYYR	SOT-23-THIN	DYY	16	3000	330.0	12.4	4.8	3.6	1.6	8.0	12.0	Q3
SN74HCS595PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

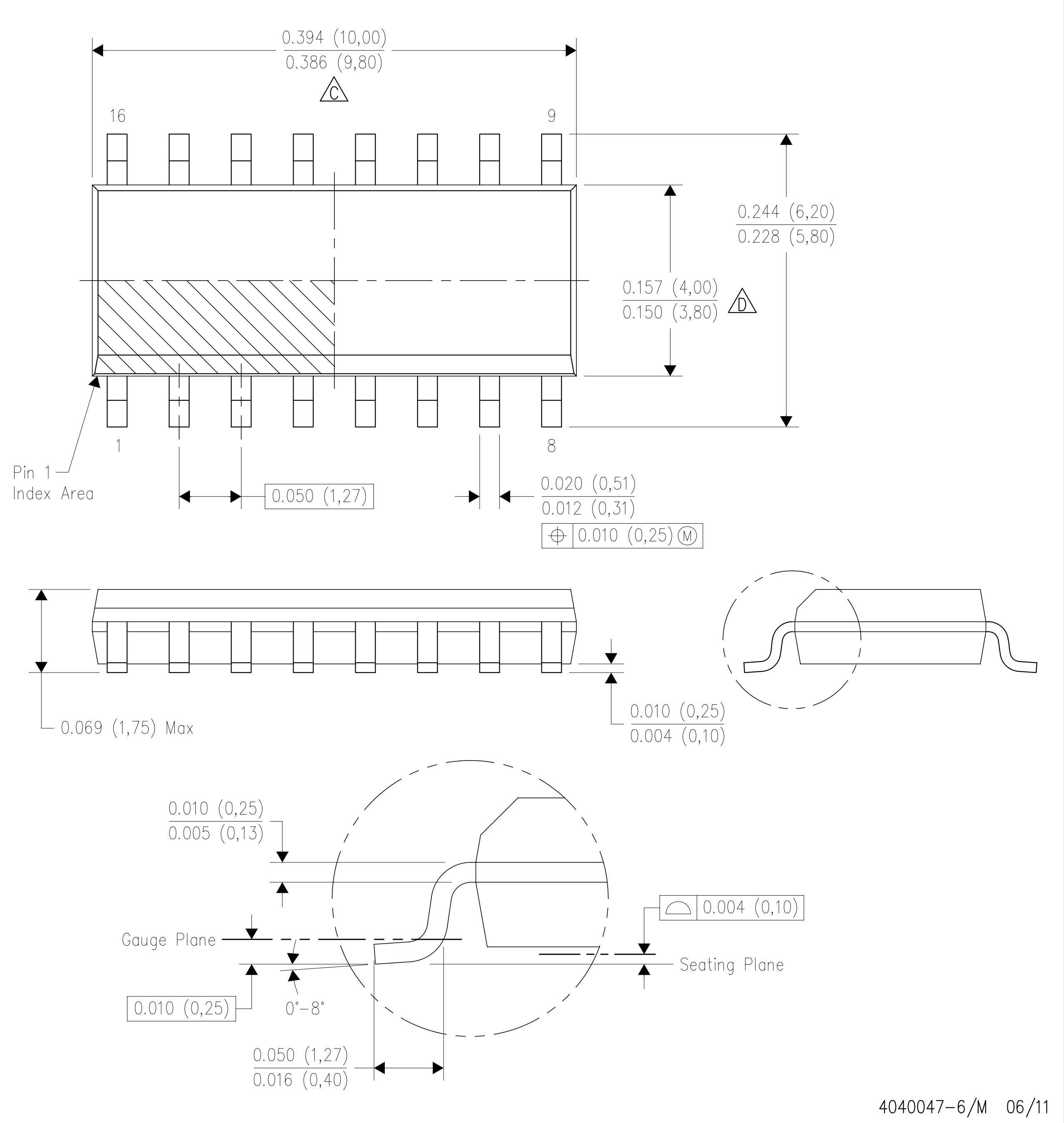
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCS595BQBR	WQFN	BQB	16	3000	210.0	185.0	35.0
SN74HCS595DR	SOIC	D	16	2500	353.0	353.0	32.0
SN74HCS595DYYR	SOT-23-THIN	DYY	16	3000	336.6	336.6	31.8
SN74HCS595PWR	TSSOP	PW	16	2000	356.0	356.0	35.0

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS–012 variation AC.

GENERIC PACKAGE VIEW

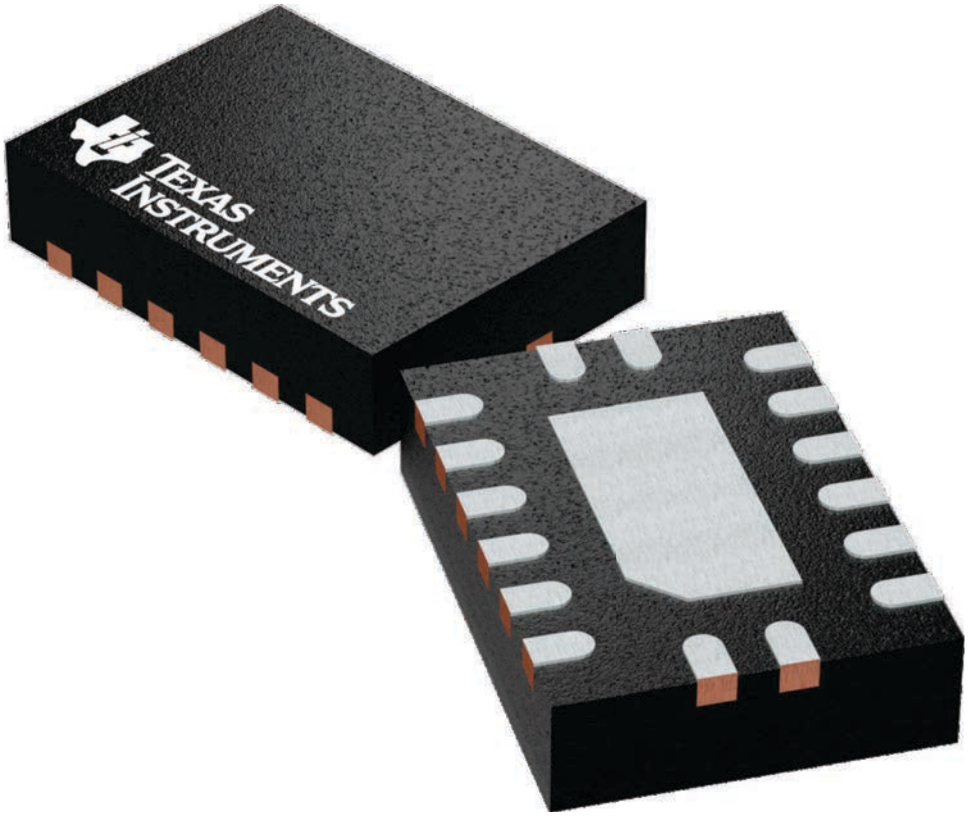
BQB 16

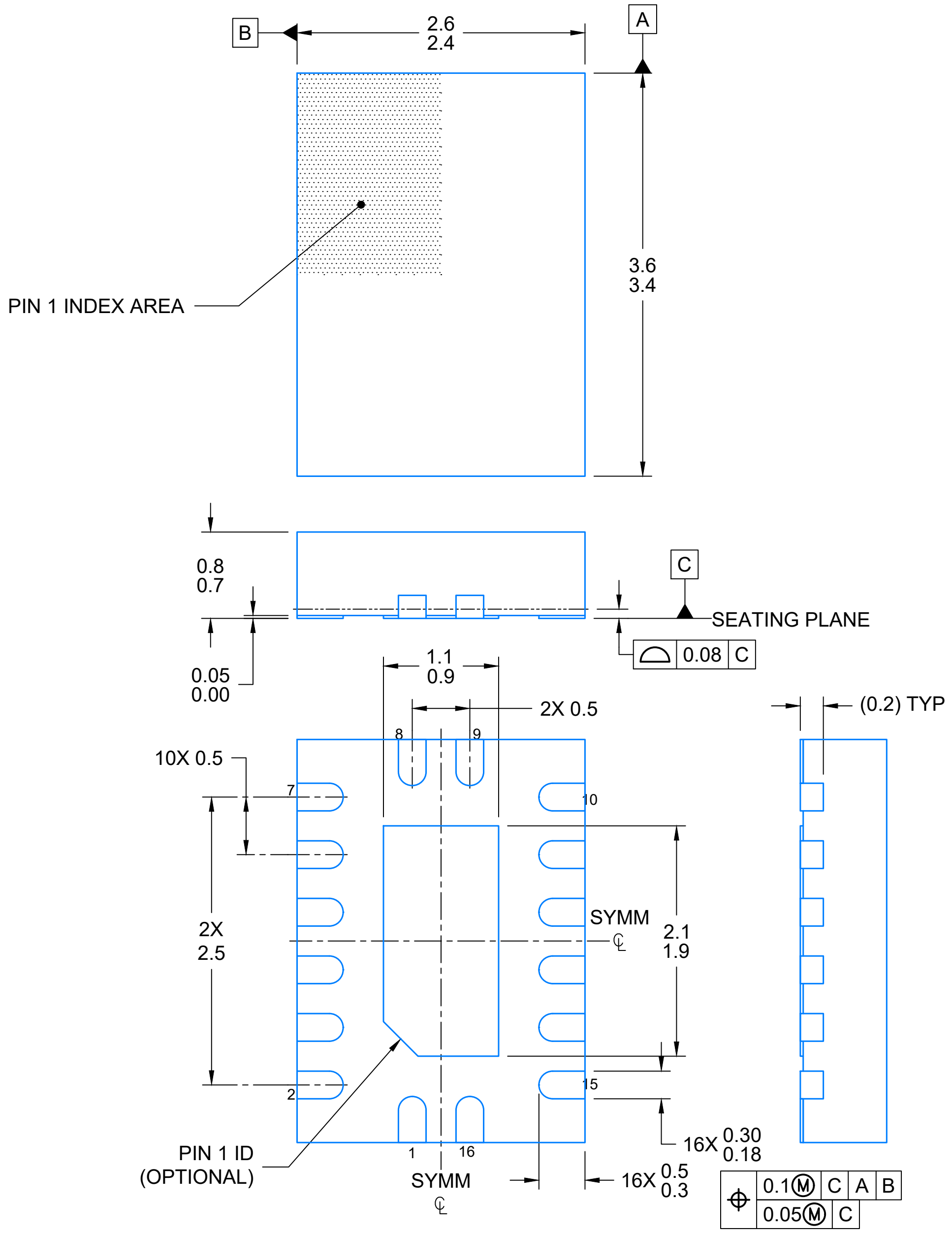
WQFN - 0.8 mm max height

2.5 x 3.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

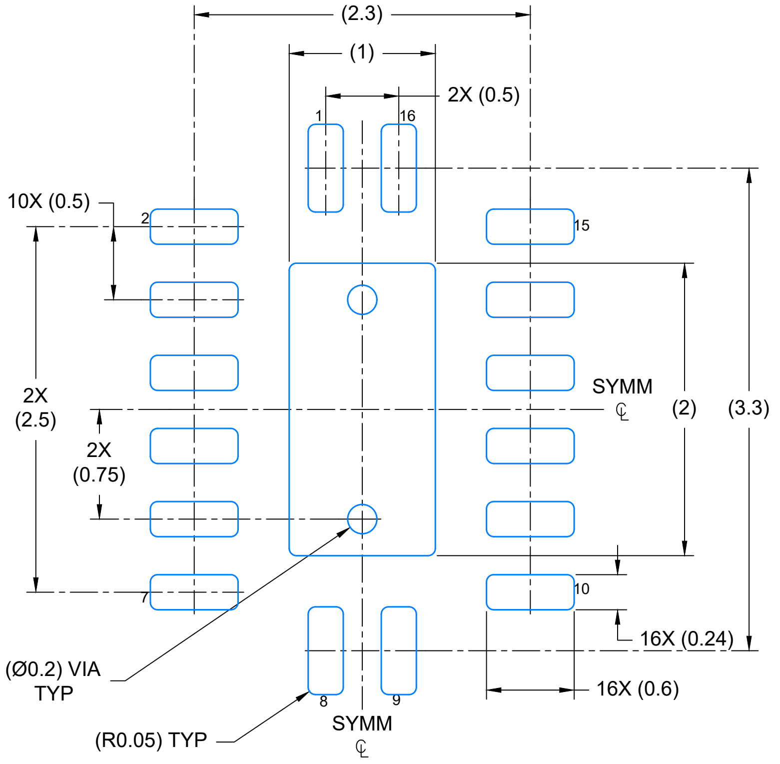




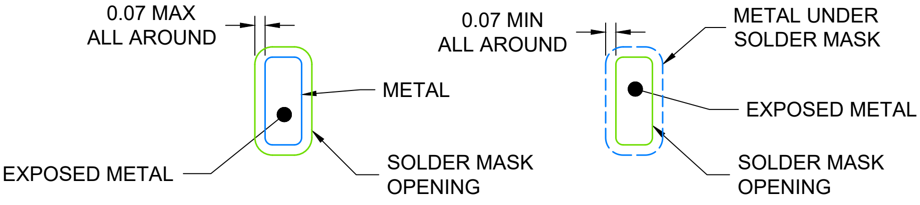
4224640/A 11/2018

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



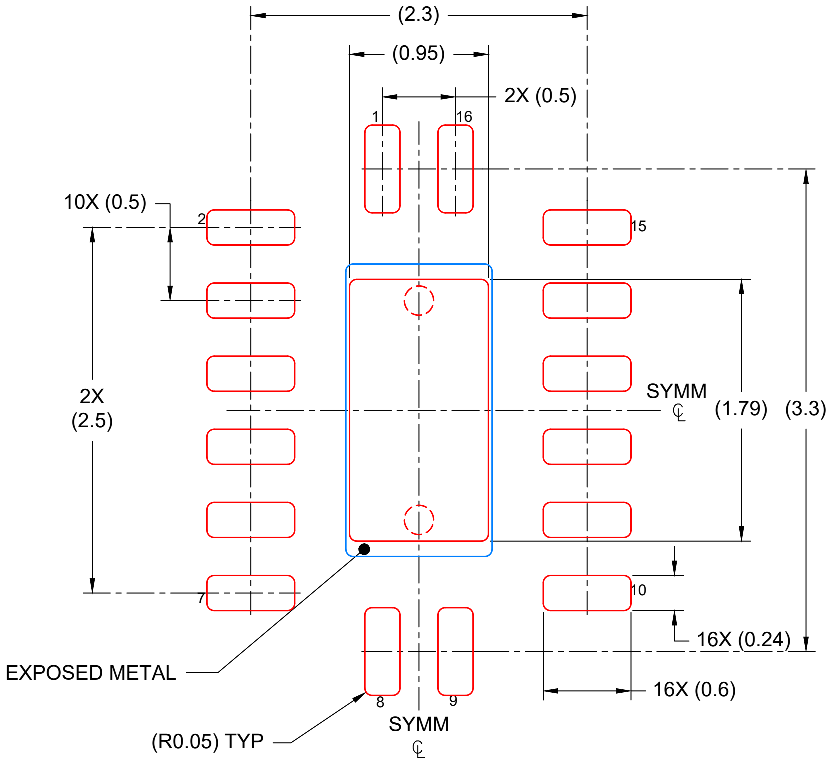
NON-SOLDER MASK
DEFINED
(PREFERRED)

SOLDER MASK
DEFINED

4224640/A 11/2018

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
85% PRINTED COVERAGE BY AREA
SCALE: 20X

NOTES: (continued)

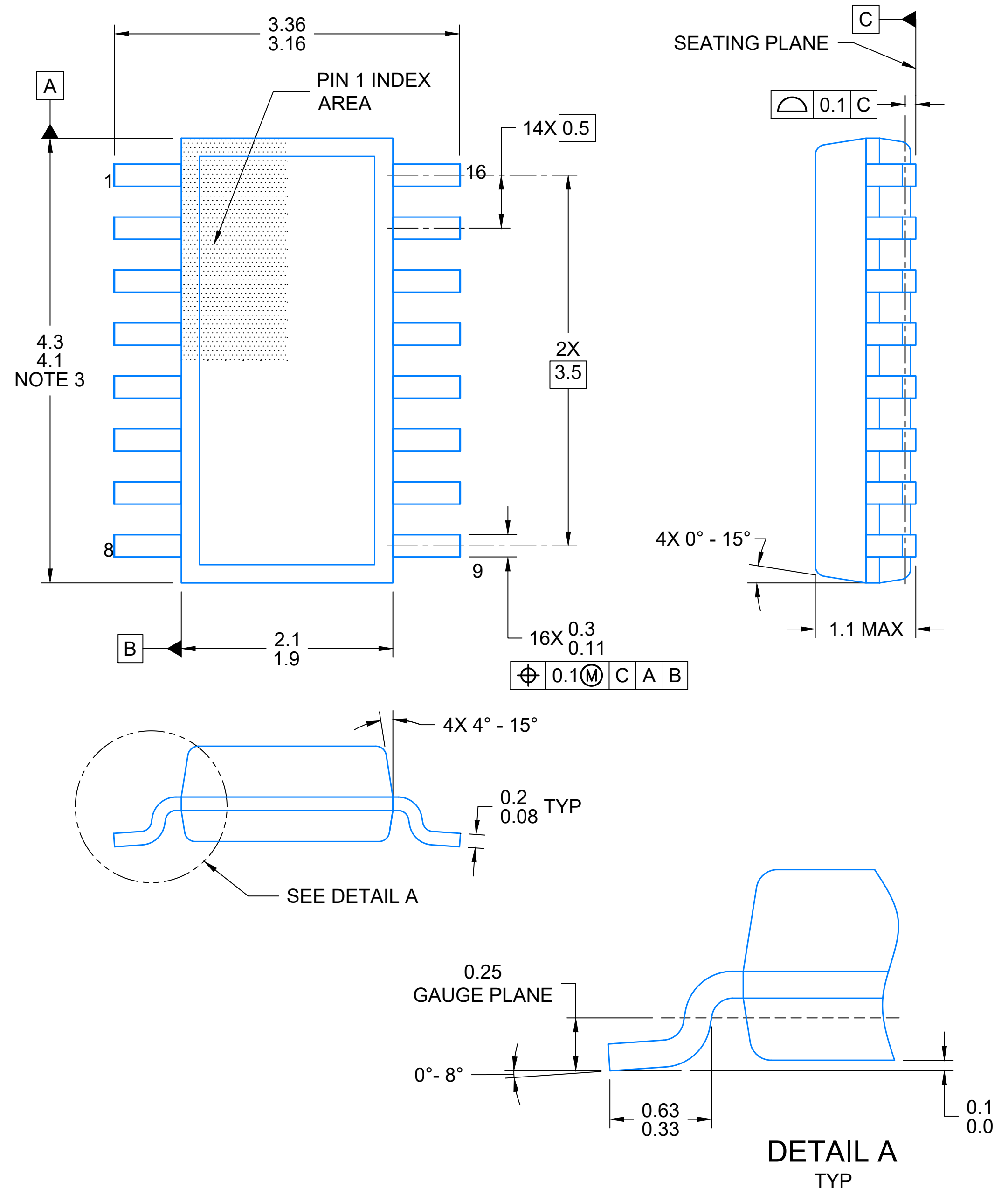
6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

PACKAGE OUTLINE

DYY0016A

SOT-23-THIN - 1.1 mm max height

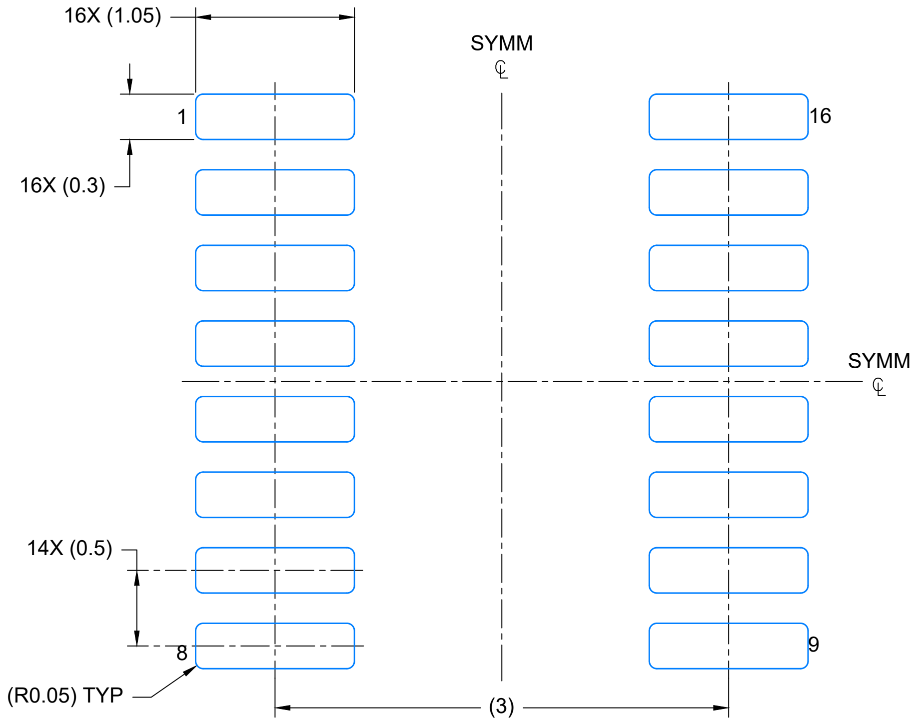
PLASTIC SMALL OUTLINE



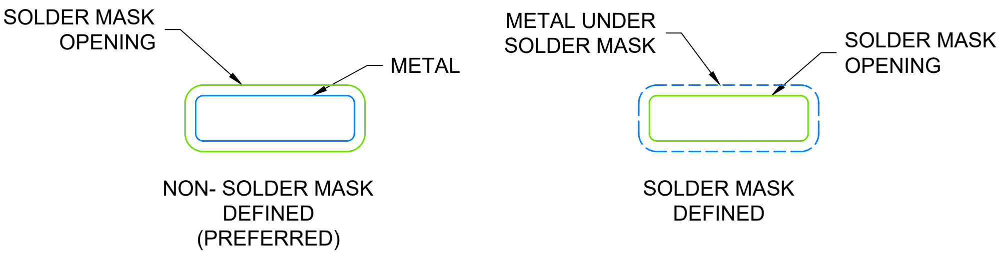
4224642/D 07/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
5. Reference JEDEC Registration MO-345, Variation AA



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X

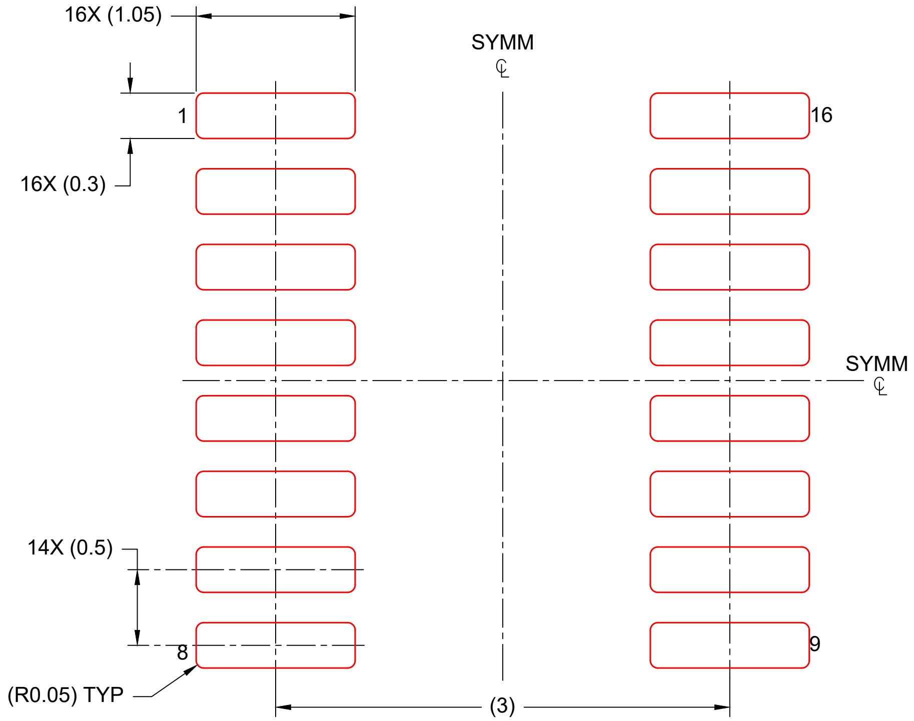


SOLDER MASK DETAILS

4224642/D 07/2024

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

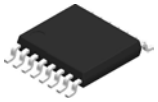


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 20X

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

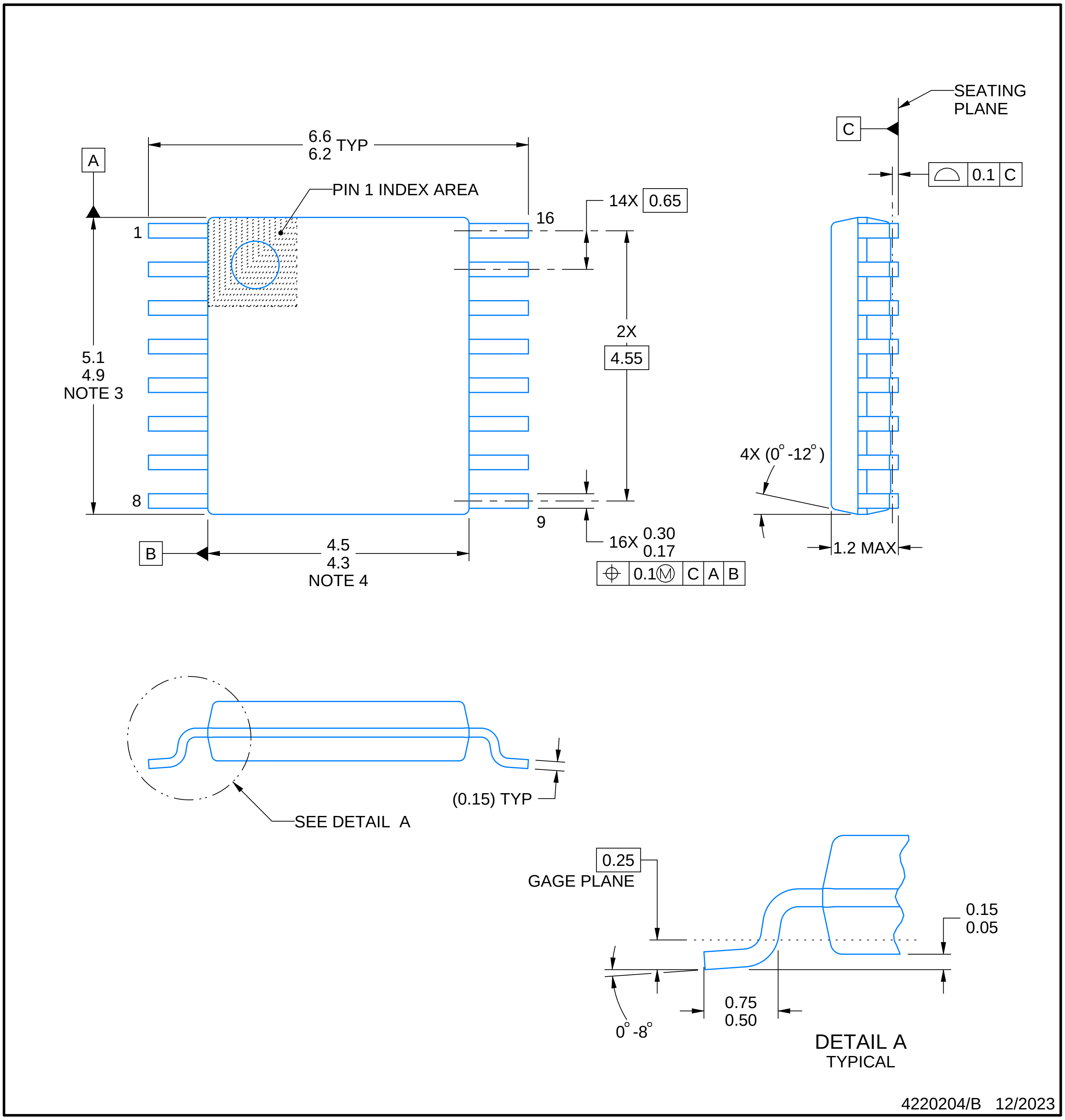
PACKAGE OUTLINE



PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

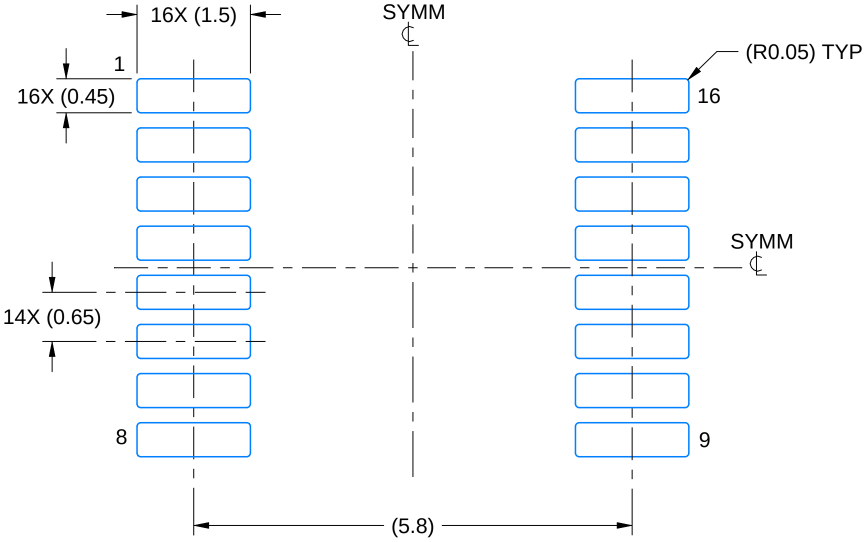


4220204/B 12/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

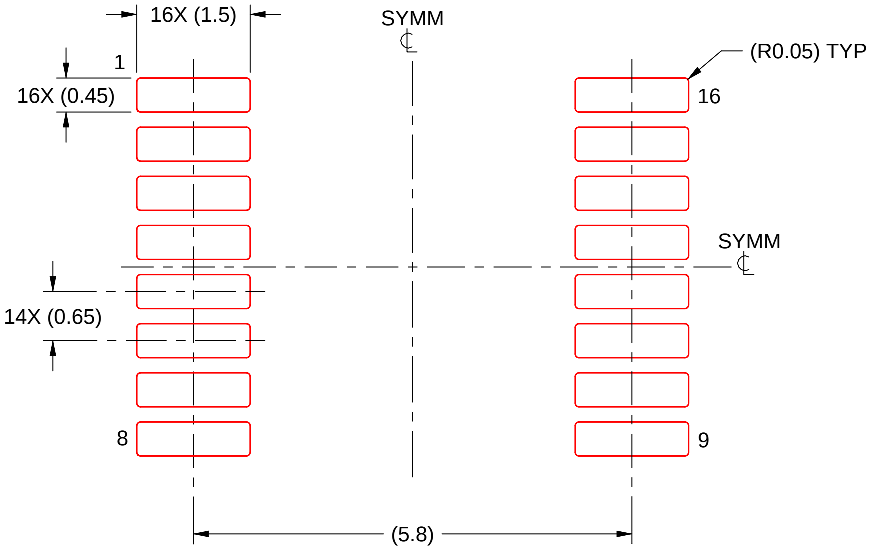
NON-SOLDER MASK
DEFINED
(PREFERRED)

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要通知和免责声明

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265